



Patent APPLICATION

Sector
Jb

In re the Application of

Akihiro MURATA

Application No.: 09/800,483

Filed: March 8, 2001

Docket No.: 108883

For: PLATFORM AND OPTICAL MODULE, MANUFACTURING METHOD OF THE
SAME, AND OPTICAL TRANSMISSION DEVICE

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 14, lines 14-22, delete current paragraph and insert therefor:

(27) An optical module according to the embodiments of the present invention comprises: the above described platform; an optical fiber inserted in the through hole; and an optical element electrically connected to the interconnecting line and mounted over the platform, wherein the optical element is provided within the indent so as to face an end surface of the optical fiber facing in the direction of the indent; and wherein a semiconductor chip which is electrically connected to the interconnecting line is further provided within the indent to face a surface of the optical element opposite to the surface facing the optical fiber.

Page 16, lines 18-24, delete current paragraph and insert therefor:

(34) This optical transmission device may further comprise: a plug connected to the optical element.

Page 18, lines 14-24, delete current paragraph and insert therefor:

When the mold 10 is formed of a material such as silicon or the like to which the metal of which the wire is formed does not adhere easily, a bonding pad 24 is preferably

09/800,483 071601